

## TRANSMITTAL FORM

I hereby certify that this correspondence is being deposited with the United States Postal Service as "Express Mail" under Label No. EV 305399265 US in an envelope addressed to Mail Stop: Patent Application, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on:

Mar 29/04 (Date of Deposit)

Kathy Dixon

Mail Stop: Patent Application Commissioner for Patents P.O. Box 1450

Alexandria, VA 22313-1450

Attorney Doc. #: 67,200-1168
Mailing Date: 729, 2004

Dear Sir:

Transmitted herewith for filing is the patent application of:

Inventor(s):

CHIEN-HSUEH SHIH, MINGHSING TSAI

For:

METHOD AND COMPOSITION TO ENHANCE WETTING OF ECP ELECTROLYTE TO COPPER

**SEED** 

Submitted herewith are:

X sheet(s) of formal drawings

X An Assignment of the invention to <u>Taiwan Semiconductor Manufacturing Co., Ltd.</u>, together with Assignment Recordal Sheet

X A Declaration for patent application under CFR 1.63 and 1.68

The filing fee has been calculated as shown below:

	No. Filed	No. Extra	Small Entity Fee	Large Entity Fee	Total
Basic Fee			\$385.00	\$770.00	\$770.00
Total Claims	20 - 20		\$9.00	\$18.00	\$0
Indep. Claims	3 -3		\$43.00	\$86.00	\$0
Multiple Dep. Clms.			\$145.00	\$290.00	\$0
Assign. Rec. Fee			\$40.00	\$40.00	\$40.00
TOTAL					\$810.00

Mailing Date: Mar. 29, 2004
Attorney Docket No.: 67,200-1/68

	Attached is a Credit Card Payment Form for the sum of \$
v	The Commissioner is hereby authorized to charge payment of the following fees associated

X The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Visa Credit Card No. <u>4756 8461 9568 0263</u>.

X
 X
 Any additional filing fees required under 37 CFR 1.6
 Any patent application processing fees under 37 CFR 1.17

Respectfully submitted,

TUNG & ASSOCIATES

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